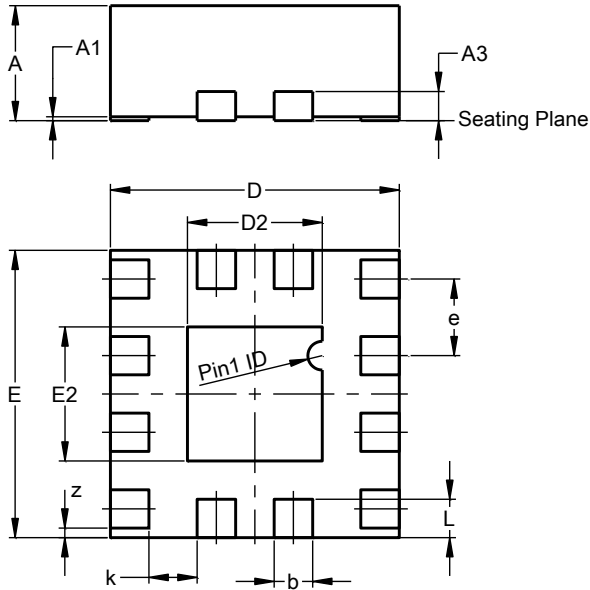


Package Outline Dimensions

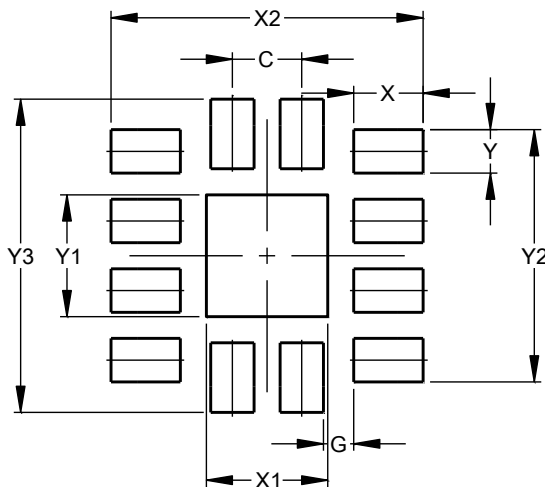
U-QFN1515-12



U-QFN1515-12			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.02
A3	0.152 BSC		
b	0.15	0.25	0.20
D	1.45	1.55	1.50
D2	0.60	0.80	0.70
E	1.45	1.55	1.50
E2	0.60	0.80	0.70
e	0.40 BSC		
L	0.15	0.25	0.20
k	--	--	0.25
z	--	--	0.050
All Dimensions in mm			

Suggested Pad Layout

U-QFN1515-12



Dimensions	Value (in mm)
C	0.400
G	0.175
X	0.400
X1	0.700
X2	1.800
Y	0.250
Y1	0.700
Y2	1.450
Y3	1.800

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

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